



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C32M16MSA-6BIN								
Part Weight:		103.980mg								
NO.	Material	Type	Component wt (mg)	Substances	Purpose	CAS No.	Element wt (%)	Weight (mg)	wt % of Total unit wt	PPM
1	Molding Compound	G1250	57.472	Epoxy Resin	Resin		5.50%	3.161	3.0400%	30,400
				Phenol resin	Resin		4.50%	2.586	2.4872%	24,872
				Silica(Fused)	filler	60676-86-0	89.70%	51.552	49.5791%	495,791
				Carbon Black	Additive	1333-86-4	0.30%	0.172	0.1658%	1,658
2	Substrate	BT	28.815	832NX-A	BT core		46.13%	13.292	12.7836%	127,836
				AUS308	Solder Mask		13.75%	3.962	3.8104%	38,104
				Cu	Trace	7440-50-8	39.37%	11.344	10.9102%	109,102
				Ni	Plating	7440-02-0	0.66%	0.190	0.1829%	1,829
				Au	Plating	7440-57-5	0.09%	0.026	0.0249%	249
3	DAF	EM700	0.895	Solid Epoxy Resin	Base material		12.50%	0.112	0.1076%	1,076
				Phenol Resin	Base material		12.50%	0.112	0.1076%	1,076
				Fused Silica	Base material	60676860	35.00%	0.313	0.3013%	3,013
				Synthrtic Rubber	Base material		40.00%	0.358	0.3443%	3,443
4	Wire	AG0B	0.472	Ag	Base material	7440-22-4	89.10%	0.421	0.4045%	4,045
				Au	Base material	7440-57-5	7.40%	0.035	0.0336%	336
				Pd	Base material	7440/5/3	3.50%	0.017	0.0159%	159
5	Solder Ball	M705	8.971	Tin (Sn)	Base material	7440-31-5	96.50%	8.657	8.3257%	83,257
				Ag	Base material	7440-22-4	3.00%	0.269	0.2588%	2,588
				Cu	Base material	7440-50-8	0.50%	0.045	0.0431%	431
6	Die	0.12mm	7.355	Si	Chip	7440-21-3	100.00%	7.355	7.0735%	70,735
								103.980	100.0000%	1,000,000